



MANUFACTURING AND ASSEMBLY OF ELECTRONIC DEVICES

Contract Manufacturing



- Complete electronic & mechanical design
- PCB design service
- Electronic and electromechanical assemblies
- Hybrid-Thick Film manufacturing
- Wire/cable assembly
- Functional testing
- Temperature cycling
- Burn-in test
- Medium volume manufacturing, prototype and low volume manufacturing
- Two surface mount manufacturing lines

SMT ASSEMBLY

- Continuous flow SMT line
- Components QFP, QFN, CSP, 0402 to □ 42mm, fine pitch ≥ 0.4 mm
- BGA, μ BGA ≥ 0.5 mm
- RoHS & non-RoHS Services
- PTH, SMT & mixed technology, Hi-Tech assembly
- Top and bottom placement with Single & double-sided assembly
- No-Clean flux process and closed loop aqueous cleaning system
- Repair and rework including BGA & QFP
- Automated Optical Inspection

HYBRID THICK FILM

- Complete thick film design capabilities
- Fast design and prototype turnarounds
- Multilayer conductors
- RoHS material
- Resistor design
- Laser trimming
- Resistor measurement
- Functional testing

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Manufacturing possibilities

- **Automatic continuous flow SMT line with 29,800 chp/h capacity:**
 - Dual vision screen printer, (SAMSUNG)
 - Two SMD automatic pick & place machines, (SAMSUNG CP45NEO)
 - Reflow soldering process with 7 temperature zones, (HELLER)
 - Automatic optical inspection, (SAMSUNG)
- **Other manufacturing equipment:**
 - Automatic wave soldering, two waves
 - Di water cleaning, 4 chambres
 - Alchocol solvent cleaning
 - Four clima chambres
 - Assembled PCB rework system

- **Prototype and low volume manufacturing line:**

- Semi-automatic screen printer
- Automatic pick and place components (SMD) positionig up to 9,700 chp/h, (SAMSUNG CP20FV)
- Reflow soldering process with 4 temperature zones, (DIMA)

